**Referenced Documents**

Procedure No. Document Description

[TA1041](file:///C:\Users\ssteffan\AppData\Local\Microsoft\Windows\INetCache\Content.Outlook\AYGV4ML6\TA1041%20Precision%20Cleaning%20User%20Guide.docx) Precision Cleaning

[TA1288](file:///C:\Users\ssteffan\AppData\Local\Microsoft\Windows\INetCache\Content.Outlook\AYGV4ML6\TA1288%20Ultrasonic%20Setup%20Procedure.docx) Ultrasonic cleaner Setup

[TA1287](file:///C:\Users\ssteffan\AppData\Local\Microsoft\Windows\INetCache\Content.Outlook\AYGV4ML6\TA1287%20Special%20Requirements%20for%20Cleanroom%20PFT%20Area.docx) Special Requirement for Cleanroom

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GENERAL INCOMING CLEANING

* + Anything entering the cleanroom that is larger than a credit card must be wiped down per procedure TA1041 Process G to reduce contaminants brought into the room.
  + Examples include, but are not limited to:
    - Job Boxes
    - Waffle packs
    - Part bags: Clear sealed, Pink reseal able, Silver ESD, etc.
    - Equipment
  + It is not necessary to wipe down sensor sub-assemblies that are contained within a clean bag or container (including pink bags) unless it is going into the ISO7 cleanroom.

PRODUCT / PART CLEANING

* + Parts contained within a cleanroom heat sealed bag do not need to be cleaned (clean package per above).
  + Product contaminants must be removed per the instruction below.
  + **All information below is unless otherwise specified in router.**

CRYSTALS, ELECTRODES, DIAPHRAGMS

Thin or fragile parts must be cleaned per procedure TA1041 Process C, taking care to assure that parts are not damaged. Do not wash diaphragms with crystals or electrodes.

\*\*Do not wash crystals with marker / indelible ink.

* + These parts can be identified by:
    - The description “Xtal”, “Electrode”, “Diaphragm”.
    - Electrodes and Diaphragms are generally very thin.
    - Crystals generally have some type of polarity mark.

RAW PARTS

All incoming raw parts must be cleaned per procedure TA1041 Process A

* + These parts are the majority of the parts that we use.
  + Examples include, but are not limited to:
    - Piston
    - Housings
    - Covers

COMPONENT SUB-ASSEMBLIES

Component Sub-assemblies must be cleaned per procedure TA1041 Process A.

* + These parts can be identified by identifying several parts assembled into one item.
  + Care must be taken when these assemblies have exposed wires that can be damaged
  + Examples include, but are not limited to:
    - Connectors
    - Charge pickup

SENSOR SUB-ASSEMBLIES, MAIN ASSEMBLIES, SENSOR ASSEMBLIES

Sensor Sub-Assemblies & Main Assemblies do not need to be cleaned, unless otherwise specified in router.

* + These parts can be identified by the description “Main Assembly”, “Subassembly”, “Element Assembly”, or by an item number that has 3-digits, a letter, and 2-3 digits (e.g. 123**A**123)
  + Examples include, but are not limited to:
    - 40530-01 **ELEMENT** ASS'Y (POSITIVE P113B A GRADE))
    - 14907-01 Q-**EL**-COMP-POSITIVE-112A21
    - 21950-01 SENSOR SUBASSEMBLY-POS-20pF-109C11/C12

AMPLIFIERS & CIRCUIT BOARDS

Amplifiers and circuit boards do not need to be washed.

* + These parts can be identified by:
    - Part number: 12345-xxx-xx
    - The description “AMP” or “VAMP” or “QAMP”

ACCESSORY PARTS

All accessory parts do not need to be cleaned, unless otherwise specified in router.

* + These parts can be identified by:
    - No item number, or item number starting with F
    - Job usually will contain a finished sensor assembly.
  + Examples include, but are not limited to:
    - Brass Seals
    - Clamp nuts
    - Kitted parts
    - Part numbers starting with:
      * 045B\_\_
      * 060A\_\_